

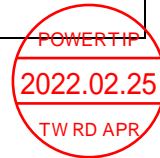
### SPECIFICATIONS

**CUSTOMER** : \_\_\_\_\_  
**SAMPLE CODE** : **SIA128800T004ZZC06**  
**MASS PRODUCTION CODE** : **HIA128800T004ZZC06**  
**SAMPLE VERSION** : **01**  
**SPECIFICATIONS EDITION** : **002**  
**DRAWING NO. (Ver.)** : **LMD-HIA128800T004ZZC06 (Ver.002)**  
**PACKAGING NO. (Ver.)** : **PKG-HIA128800T004ZZC06 (Ver.001)**

**Customer Approved**

**Date:**

Approved	Checked	Designer
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- Preliminary specification for design input
- Specification for sample approval

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## Contents

### 1. SPECIFICATIONS

- 1.1 Features
- 1.2 Mechanical Specifications
- 1.3 Absolute Maximum Ratings
- 1.4 DC Electrical Characteristics
- 1.5 Optical Characteristics

### 2. MODULE STRUCTURE

- 2.1 Counter Drawing
- 2.2 Connector list
- 2.3 Interface Pin Description

### 3. QUALITY ASSURANCE SYSTEM

- 3.1 Quality Assurance Flow Chart

### 4. RELIABILITY TEST

- 4.1 Reliability Test Condition

### 5. PRECAUTION RELATING PRODUCT HANDLING

- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- 5.4 Terms of Warranty

#### Appendix :

- 1. Drawing
- 2. Packaging Specifications
- 3. Assembly Guide

## 1. SPECIFICATIONS

### 1.1 Features

#### Hardware

<b>CPU</b>	RISC Processor	i.MX8M Mini Quad Cortex-A53 @ 1.6 GHz
<b>Memory</b>	On Board RAM	2GB LPDDR4 SDRAM
	On Board ROM	8GB eMMC Flash
	External Storage	1x Micro SD (max. 32G)
<b>Display</b>	Resolution	1280 (RGB) x 800 DOTS
	Display mode	Transmissive, Normally Black
	Screen Size	10.1 inch
	Touch Panel	Projected Capacitive Touch (USB)
<b>I/O</b>	Display Interface	1x MIPI DSI 1x LVDS
	USB	1x USB OTG 2x USB1.1/2.0 Compliant Host 1x USB1.1/2.0 in Mini-PCle Connector
	PCI Express	1x Mini-PCle Connector(1-lane)
	Ethernet	10/100/1000 Mbps
	Analog Audio	1 x Headphone Jack 1 x Input
	Wireless	WIFI IEEE 802.11 a/b/g/n/ac Bluetooth 4.2
	Serial	2 x UART (one for Debug Used) 4 x I2C 1 x SPI
<b>Power Input</b>	DC	9V ~ 24V

#### Software

<b>OS</b>	Embedded	Android / Yocto Linux
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## 1.2 Mechanical Specifications

Item	Standard Value	Unit
Board Outline Dimension	118.5(W) x 87.5 (L) x 25.0(H) MAX	mm
Display Active Area	216.96 (W) * 135.6 (L)	mm

## 1.3 Absolute Maximum Ratings

Ta = 25°C

Item	Symbol	Condition	Min.	Max.	Unit
Power Supply	V <sub>IN</sub>	—	-0.3	26.0	V
Operating Temperature	T <sub>OP</sub>	—	-20	70	°C
Storage Temperature	T <sub>ST</sub>	—	-30	80	°C
Humidity	H <sub>D</sub>	Ta=60 °C	10	90	%RH

## 1.4 DC Electrical Characteristics

Ta = 25°C

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply Voltage	V <sub>IN</sub>	-	9	12	24	V
Power Supply Current	I <sub>IN1</sub>	V <sub>IN</sub> = 12V	-	890	-	mA
IO High-Level input voltage	V <sub>IH</sub>	-	0.7xV <sub>DD3V3</sub>	-	V <sub>DD3V3</sub> +0.3	V
IO Low-Level input voltage	V <sub>IL</sub>	-	-0.3	-	0.3xV <sub>DD3V3</sub>	V
IO High-Level output voltage	V <sub>OH</sub>	-	-	-	3.6	V
IO Low-Level output voltage	V <sub>OL</sub>	-	-0.3	-	-	V

Note 1: V<sub>IN</sub> is connected to 'J4' connector.

## 1.5 Optical Characteristics

Ta=25°C

Item	Symbol	Condition	Min.	Typ.	Max.	unit	-	
Response time	Tr + Tf	-	-	25	50	ms	Note2	
Viewing angle	Top	$\theta Y+$	CR $\geq$ 10	-	85	-	Deg.	Note4
	Bottom	$\theta Y-$		-	85	-		
	Left	$\theta X+$		-	85	-		
	Right	$\theta X-$		-	85	-		
Contrast ratio	CR	-	600	800	-	-	Note3	
Color of CIE Coordinate (With B/L and TP)	White	X	IF= 20mA	0.26	0.31	0.36	-	Note1
		Y		0.30	0.35	0.40		
	Red	X		0.55	0.60	0.65		
		Y		0.29	0.34	0.39		
	Green	X		0.27	0.32	0.37		
		Y		0.54	0.59	0.64		
	Blue	X		0.10	0.15	0.20		
		Y		0.11	0.16	0.21		
Average Brightness Pattern=white display (With B/L and TP)	IV	IF= 20mA	700	800	-	cd/m <sup>2</sup>		
Luminance Uniformity	YU	-	70	-	-	%		

Note 1:

\*1 :  $\Delta B = B(\min) / B(\max) * 100\%$

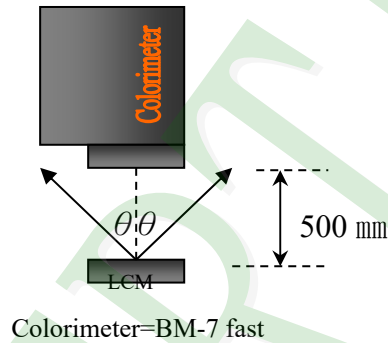
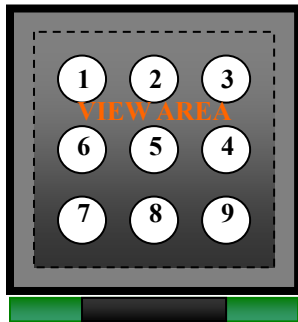
\*2 : Measurement Condition for Optical Characteristics:

a : Environment:  $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$  /  $60 \pm 20\%$  R.H , no wind , dark room below 10 Lux at typical lamp current and typical operating frequency.

b : Measurement Distance:  $500 \pm 50$  mm , ( $\theta = 0^{\circ}$ )

c : Equipment: TOPCON BM-7 fast , (field  $1^{\circ}$ ) , after 10 minutes operation.

d : The uncertainty of the C.I.E coordinate measurement  $\pm 0.01$  , Average Brightness  $\pm 4\%$



To be measured at the center area of panel with a viewing cone of  $1^{\circ}$  by Topcon luminance meter BM-7, after 10 minutes operation (module)

Note2: Definition of response time:

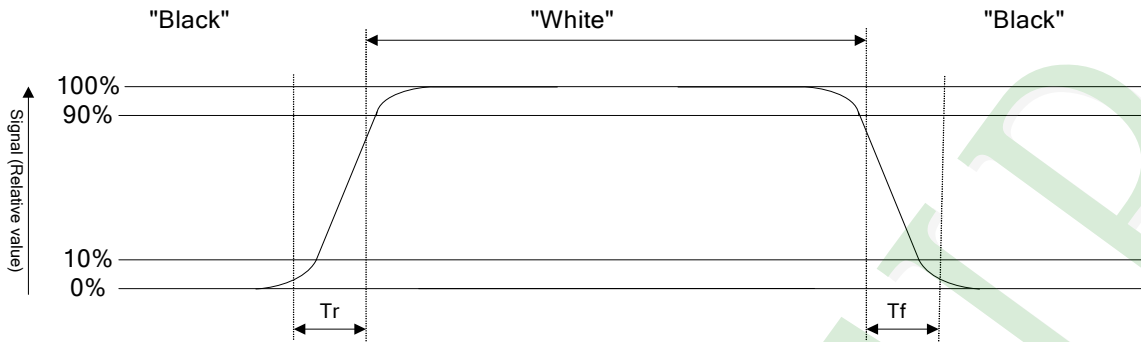
The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of Amplitudes.

Refer to figure as below:

Normally White



### Normally Black



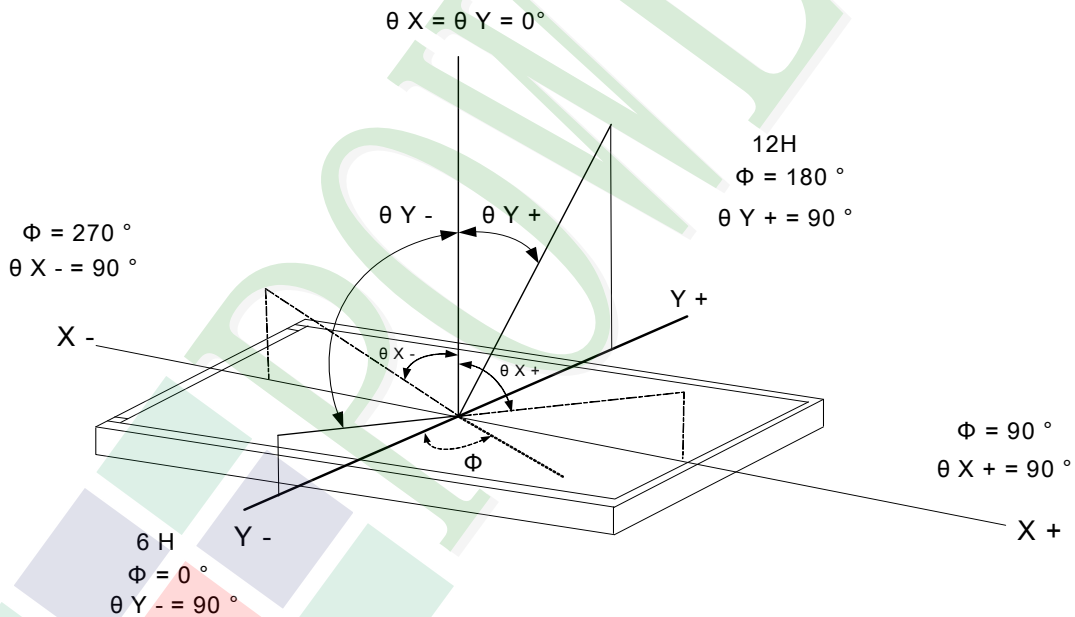
Note3: Definition of contrast ratio:

Contrast ratio is calculated with the following formula

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" state}}{\text{Photo detector output when LCD is at "Black" state}}$$

Note4: Definition of viewing angle:

Refer to figure as below:





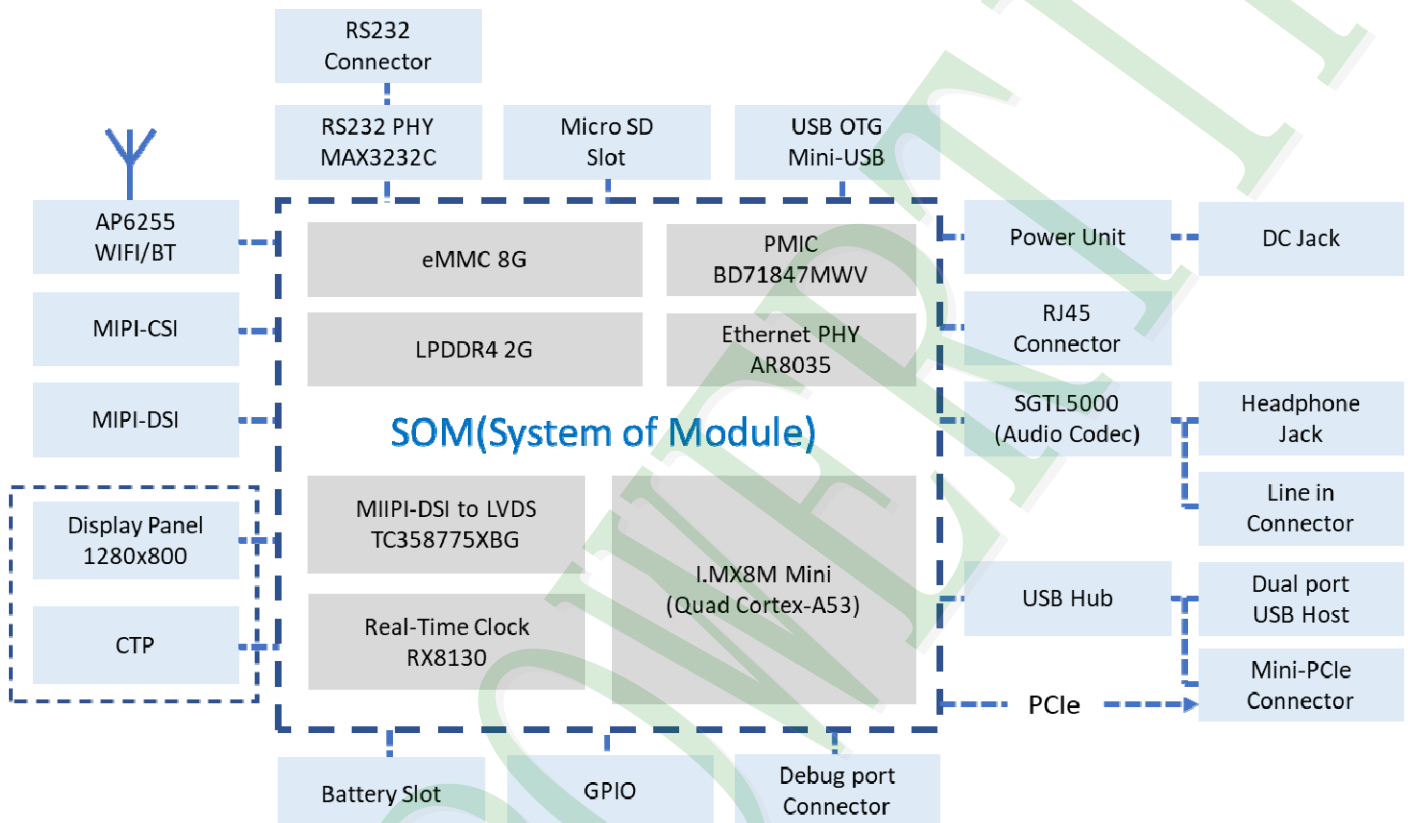
## 2. MODULE STRUCTURE

### 2.1 Counter Drawing

#### 2.1.1 LCM Mechanical Diagram

\* See Appendix

#### 2.1.2 Block Diagram



## 2.2 Connector list

Symbol	Description	Note
J2	Extension Power Pin	
J3	RTC Power Supply (Pitch 1.25mm)	
J4	Power Supply (DC Jack)	
J5	Audio Signal Input (Pitch 1.25mm)	
J6	Antenna Connector	
J8	-	No Function
J9	Display – MIPI DSI (Pitch 0.5mm 30pin)	
J11	CTP Interface (Pitch 1.25mm 6pin)	
J12	CTP Interface (Pitch 0.5mm 6pin)	
J13	-	No Function
J14	Display – LVDS0 (Pitch 2.0mm 2x20pin)	(Display Panel)
J15	-	No Function
J16	Backlight Power (Pitch 2.0mm 6 pin)	(Display Backlight)
J17	USB 1.1/2.0 Host (Pitch 1.25mm, 5pin)	(CTP)
J18	Micro SD Card	
J19	USB 2.0 Device USB Port Mini-B (USB OTG)	
J20	USB 1.1/2.0 Host USB Port Type A	
J22	Mini-PCIe Connector	
J23	Power Output (Pitch 1.25mm)	
J25	UART2 Debug (Pitch 1.25mm 4pin)	
J26	RS232 (Pitch 2.0mm 2x5pin)	
J28	-	No Function
J29	GPIO (Pitch 2.0mm 2x10pin)	
J30	Camera – MIPI CSI (Pitch 0.5mm 30pin)	
J31	-	No Function
J34	Ethernet RJ45	
CN2	Standard Headphone Jack $\varnothing$ 3.5mm.	
SW1	Reset Button	
SW2	ON/OFF Power Button	
JP1	Boot Switch	
BAT1	Battery	

## 2.3 Interface Pin Description

### J2 --- Extension Power Pin (Pitch 1.25mm)

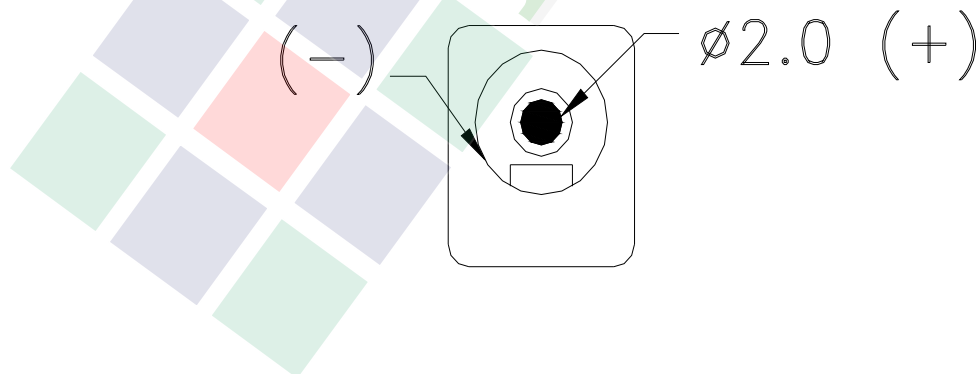
Pin No.	Symbol	Type	DESCRIPTION
1	PWEN		Power Indicator LED (LED1)
2	NC	-	-
3	BTN RSTINn	P	As Reset Button, SW1 (Active Low)
4	NC	-	-
5	ONOFF	P	As ONOFF Power Button, SW2 (Active Low)
6	GND	P	Ground

### J3 --- RTC Power Supply (Pitch 1.25mm)

Pin No.	Symbol	Type	DESCRIPTION
1	GND	P	Ground
2	V <sub>BAT</sub>	P	RTC Power Supply

### J4 --- System Power Supply

Pin No.	Symbol	Type	DESCRIPTION
+	V <sub>IN</sub>	P	DC Power Supply of System
-	GND	P	Ground



### J5 --- Audio Signal Input (Pitch 1.25mm)

Pin No.	Symbol	Type	DESCRIPTION
1	LINEINL	A	Line-in Left Channel Input
2	LINEINR	A	Line-in Right Channel Input
3	GND	P	Ground
4	GND	P	Ground

### Display Interface --- MIPI DSI (J9 – Pitch 0.5mm 30pin)

Function	Symbol	Type	DESCRIPTION	J9
Power	V <sub>LCD3V3</sub>	P	+3.3V Power Supply for Display Module	3, 4
	V <sub>DD3V3</sub>	P	+3.3V Output	7
	V <sub>DD5V</sub>	P	+5.0V Output	1,2
	GND	P	Ground	6, 8, 13, 15, 18, 21, 24, 27, 30
MIPI DSI Signal	MIPI_CLK_N	DS	MIPI DSI Clock Negative	26
	MIPI_CLK_P		MIPI DSI Clock Positive	25
	MIPI_D0_N		MIPI DSI Data 0 Negative	29
	MIPI_D0_P		MIPI DSI Data 0 Positive	28
	MIPI_D1_N		MIPI DSI Data 1 Negative	23
	MIPI_D1_P		MIPI DSI Data 1 Positive	22
	MIPI_D2_N		MIPI DSI Data 2 Negative	20
	MIPI_D2_P		MIPI DSI Data 2 Positive	19
	MIPI_D3_N		MIPI DSI Data 3 Negative	17
	MIPI_D3_P		MIPI DSI Data 3 Positive	16
Other	I2C4_SDA	IO	I2C Port4 Serial Data	9
	I2C4_SCL	IO	I2C Port4 Serial Clock	10
	CTP_RST	O	CTP Reset Signal	11
	CTP_INT	I	CTP Interrupt Signal	12
	GPIO3_IO23	IO	General-Purpose I/O	14

### J11, J12 --- CTP Interface (J11 – Pitch 1.25mm 6pin, J12 – Pitch 0.5mm 6pin)

Pin No.	Symbol	Type	DESCRIPTION
1	GND	P	Ground
2	V <sub>DD3V3</sub>	P	+3.3V
3	I2C4_SCL	IO	I2C Port3 Serial Clock
4	I2C4_SDA	IO	I2C Port3 Serial Data
5	CTP_INT	I	CTP Interrupt Signal
6	CTP_RST	O	CTP Reset Signal

### Display Interface --- LVDS (J14 – Pitch 2.0mm, 2x20pin)

Function	Symbol	Type	DESCRIPTION	J14
Power	V <sub>LCD3V3</sub>	P	+3.3V Power Supply for Display Module	1,2,3
	V <sub>DD5V</sub>	P	+5.0V Output	39
	GND	P	Ground	4, 5, 6, 13, 14, 19, 20, 22, 31, 32, 40
LVDS 0 Signal	LVDS0_TX0_N	DS	LVDS Chanel 0 Data 0 Negative	7
	LVDS0_TX0_P		LVDS Chanel 0 Data 0 Positive	8
	LVDS0_TX1_N		LVDS Chanel 0 Data 1 Negative	9
	LVDS0_TX1_P		LVDS Chanel 0 Data 1 Positive	10
	LVDS0_TX2_N		LVDS Chanel 0 Data 2 Negative	11
	LVDS0_TX2_P		LVDS Chanel 0 Data 2 Positive	12
	LVDS0_CLK_N		LVDS Chanel 0 Clock Negative	15
	LVDS0_CLK_P		LVDS Chanel 0 Clock Positive	16
	LVDS0_TX3_N		LVDS Chanel 0 Data 0 Negative	17
	LVDS0_TX3_P		LVDS Chanel 0 Data 0 Positive	18
Others	I2C4_SDA	IO	I2C Port4 Serial Data	37
	I2C4_SCL	IO	I2C Port4 Serial Clock	35
	GPIO3_IO22	IO	General-Purpose I/O	21
	CTP_INT	O	CTP Interrupt Signal	36
	CTP_RST	O	CTP Reset Signal	38
	NC	-	Not Connection	23, 24, 25, 26, 27, 28, 29, 30, 33, 34

**J16 --- Backlight Power (Pitch 2.0mm 6pin)**

Pin No.	Symbol	Type	DESCRIPTION
1	VBLOUT	P	VBLOUT is connected to $V_{IN}$ directly
2	VBLOUT	P	VBLOUT is connected to $V_{IN}$ directly
3	GPIO0_IO00	O	General-Purpose I/O
4	PWM1	IO	PWM signal output for backlight
5	GND	P	Ground
6	GND	P	Ground

**J23 --- Power Output (Pitch 1.25mm)**

Pin No.	Symbol	Type	DESCRIPTION
1	$V_{DD5V}$	P	+5.0V Output
2	$V_{DD5V}$	P	+5.0V Output
3	GND	P	Ground
4	GND	P	Ground

**J25 --- UART Debug (Pitch 1.25mm, 4pin)**

Pin No.	Symbol	Type	DESCRIPTION
1	$V_{DD3V3}$	P	+3.3V Output
2	UART2_TXD	IO	UART2 Transmitter Signal (3.3V Level)
3	UART2_RXD	IO	UART2 Receiver Signal (3.3V Level)
4	GND	P	Ground

**J17 --- USB 1.1/2.0 Host (Pitch 1.25mm, 5pin)**

Pin No.	Symbol	Type	DESCRIPTION
1	V <sub>USB5V</sub>	P	+5.0V USB Power Supply
2	D-	DS	Data – (Data M)
3	D+	DS	Data + (Data P)
4	GND	P	Ground
5	GND	P	Ground

**J19 --- USB 2.0 Device USB Port Mini-B (USB OTG)**

Pin No.	Symbol	Type	DESCRIPTION
1	V <sub>USB5V</sub>	P	+5.0V USB Power Supply
2	D-	DS	Data – (Data M)
3	D+	DS	Data + (Data P)
4	ID	-	USB ID
5	GND	P	Ground

**J20 --- USB 1.1/2.0 Host USB Port Type A \* 2**

Pin No.	Symbol	Type	DESCRIPTION
1	V <sub>DD5V</sub>	P	+5.0V Output
2	D-	DS	Data – (Data M)
3	D+	DS	Data + (Data P)
4	GND	P	Ground

## J22 --- Mini-PCle Connector

Function	Symbol	Type	DESCRIPTION	J30
Power	V <sub>DD3V3</sub>	P	+3.3V Output	2, 24, 39, 41, 52
	V <sub>DD1V5</sub>	P	+1.5V Output	6, 28, 48
	GND	P	Ground	4, 9, 15, 18, 21, 26, 27, 29, 34, 35, 37, 40, 43, 50
PCIe	PCIE_RX_N	DS	PCIE Receiver Signal -	23
	PCIE_RX_P		PCIE Receiver Signal +	25
	PCIE_TX_N		PCIE Transmitter Signal -	31
	PCIE_TX_P		PCIE Transmitter Signal +	33
	PCIE_CLK_N		PCIE Clock Signal -	11
	PCIE_CLK_P		PCIE Clock Signal +	13
	PCIE_WAKE	IO	Wake Up Signal	1
	PCIE_RESET		Reset Signal	22
	PCIE_DISABLE		Disable Signal	20
USB	USB_D_N	DS	Data - (Data M)	36
	USB_D_P		Data + (Data P)	38
I2C	I2C2_SCL	IO	I2C Port2 Serial Clock	30
	I2C2_SDA		I2C Port2 Serial Data	32
Other	LED_WWAN	-	LED P1	42
	LED_WLAN	-	LED P2	44
	LED_WPAN	-	LED P3	46
	NC	-	Not Connection	3, 5, 7, 8, 10, 12, 14, 16, 17, 19, 45, 47, 49, 51



**J26 --- RS232 (Pitch 2.0mm, 2x5pin)**

Pin No.	Symbol	Type	DESCRIPTION
1	NC	-	Not Connection
2	RS232_RXD	I	RS232 Receiver Signal (UART3, RS232 level)
3	RS232_TXD	O	RS232 Transmitter Signal (UART3, RS232 level)
4	VDD3V3	P	+3.3V Output
5	GND	P	Ground
6	NC	-	Not Connection
7	NC	-	Not Connection
8	NC	-	Not Connection
9	NC	-	Not Connection
10	GND	P	Ground

**J29 --- GPIO (Pitch 2.0mm, 2x10pin)**

Pin No.	Symbol	Type	DESCRIPTION
1	V <sub>DD3V3</sub>	P	+3.3V Output
2	V <sub>DD5V</sub>	P	+5.0V Output
3	GND	P	Ground
4	GND	P	Ground
5	UART4_TXD	IO	<b>M4 Debug</b> - UART4 Transmitter Signal (3.3V Level)
6	GPIO3_IO22	IO	General-Purpose I/O
7	UART4_RXD	IO	<b>M4 Debug</b> - UART4 Receiver Signal (3.3V Level)
8	I2C3_SCL	IO	I2C3 serial clock
9	GPIO3_IO01	IO	General-Purpose I/O
10	I2C3_SDA	IO	I2C3 serial Data
11	GPIO3_IO00	IO	General-Purpose I/O
12	ECSPI2_SS0	IO	CSPI2 Chip Select Signal 0
13	GPIO3_IO25	IO	General-Purpose I/O
14	ECSPI2_SCLK	IO	CSPI2 Serial Clock Signal
15	GPIO3_IO08	IO	General-Purpose I/O
16	ECSPI2_MISO	IO	CSPI2 MISO Serial Data Signal
17	GPIO3_IO09	IO	General-Purpose I/O
18	ECSPI2_MOSI	IO	CSPI2 MOSI Serial Data Signal
19	GND	P	Ground
20	GND	P	Ground

## Camera Interface --- MIPI CSI (J30 – Pitch 0.5mm 30pin connector bottom contact)

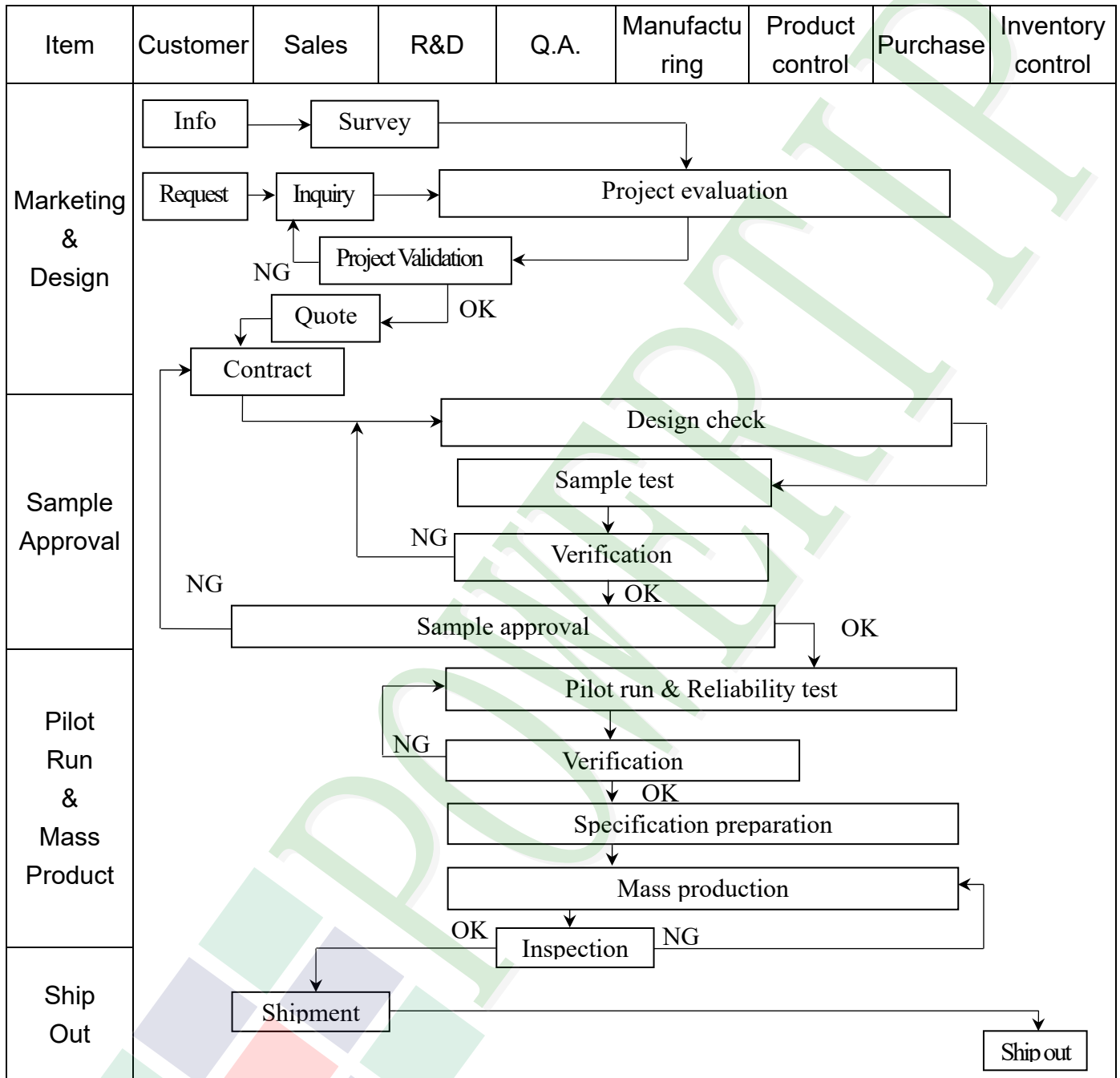
Function	Symbol	Type	DESCRIPTION	J30
Power	V <sub>DD5V</sub>	P	+5.0V Output	1
	V <sub>DD1V8</sub>	P	I/O voltage for Camera module	4
	GND	P	Ground	6, 8, 13, 15, 18, 21, 24, 27, 30
MIPI CSI Signal	MIPI_C_CLK_N	DS	MIPI CSI Clock Negative	26
	MIPI_C_CLK_P		MIPI CSI Clock Positive	25
	MIPI_C_D0_N		MIPI CSI Data 0 Negative	29
	MIPI_C_D0_P		MIPI CSI Data 0 Positive	28
	MIPI_C_D1_N		MIPI CSI Data 1 Negative	23
	MIPI_C_D1_P		MIPI CSI Data 1 Positive	22
	MIPI_C_D2_N		MIPI CSI Data 2 Negative	20
	MIPI_C_D2_P		MIPI CSI Data 2 Positive	19
	MIPI_C_D3_N		MIPI CSI Data 3 Negative	17
	MIPI_C_D3_P		MIPI CSI Data 3 Positive	16
Other	CAM_SDA	IO	I2C2 Serial Data (1.8V Level)	9
	CAM_SCL	IO	I2C2 Serial Clock (1.8V Level)	10
	CSI_RESET	O	Reset Signal for Camera module (1.8V Level)	11
	CSI_CLKO	O	Clock output to Camera module (1.8V Level)	14
	NC	-	Not Connection	2, 3, 5, 7, 12

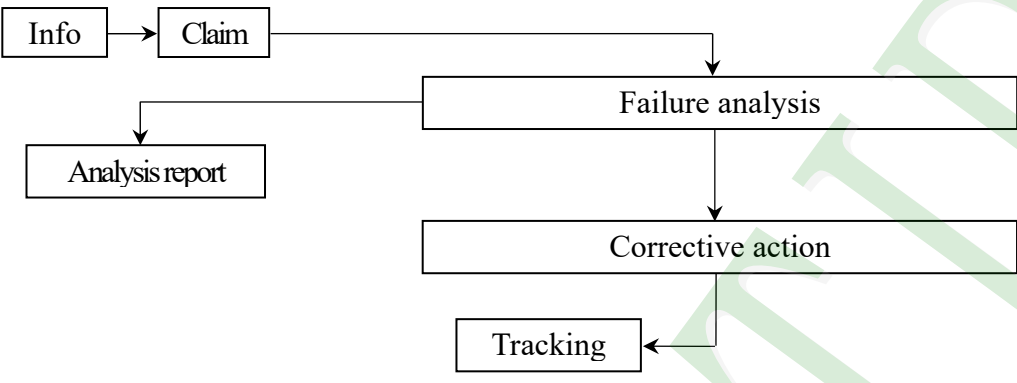
## JP1 --- Boot Switch

JP1[1:2]		BOOT_MODE [1:0]	Boot Type
ON	ON	00	Boot from Fuses
ON	OFF	01	Serial Downloader (USB OTG Port)
OFF	ON	10	Internal Boot (eMMC)
OFF	OFF	11	Reserved

### 3. QUALITY ASSURANCE SYSTEM

#### 3.1 Quality Assurance Flow Chart



Item	Customer	Sales	R&D	Q.A.	Manufacturing	Product control	Purchase	Inventory control
Sales Service	 <pre> graph TD     Info[Info] --&gt; Claim[Claim]     Claim --&gt; Failure[Failure analysis]     Failure --&gt; Report[Analysis report]     Failure --&gt; Action[Corrective action]     Action --&gt; Tracking[Tracking]           </pre>							
Q.A Activity	1. ISO 9001 Maintenance Activities 3. Equipment calibration 5. Standardization Management				2. Process improvement proposal 4. Education and Training Activities			



## 5. PRECAUTION RELATING PRODUCT HANDLING

### 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

### 5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonic solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is  $320 \pm 10^{\circ}\text{C}$  and 3 ~ 5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.
- 5.2.10 Caution! (LCM products with Capacitive Touch Panel)  
Strong EMI-sources such as switch-mode power supplies (SPS) can lead to touch malfunction (e.g., ghost-touches). Therefore, the touch needs to be thoroughly tested inside the target application.
- 5.2.11 CAUTION: Continuously displaying same static image will result in high possibility of image sticking/image burn-in effect due to TFT panel characteristic.
- 5.2.12 Double-sided tape designed to be attached with the customer's mechanical device, please follow up the rules and regulations published by the original manufacturer of double-side tape for the attachment operation.

### 5.3 STORAGE

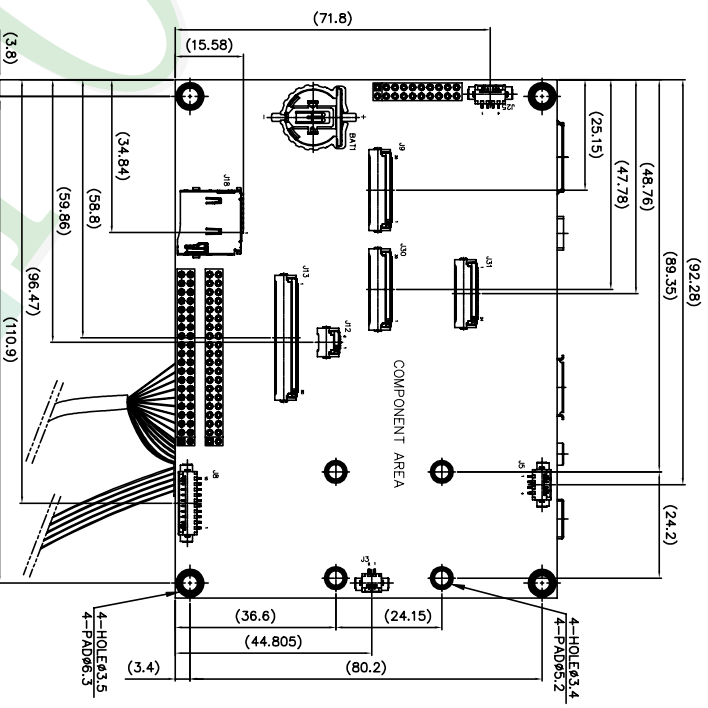
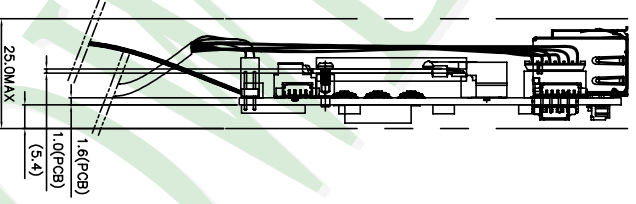
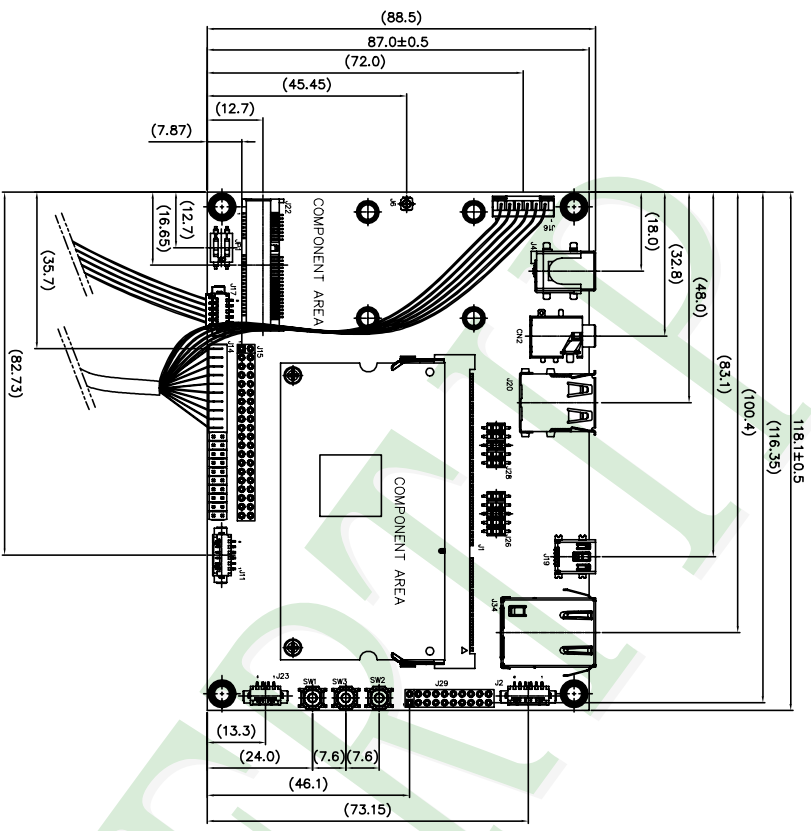
- 5.3.1 Store the panel or module in a dark place where the temperature is  $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$  and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

### 5.4 TERMS OF WARRANTY

- 5.4.1 Applicable warrant period  
The period is within thirteen months since the date of shipping out under normal using and storage conditions.
- 5.4.2 Unaccepted responsibility  
This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.







Detail SBC Board  
Scale 1X

- NOTES:
- 5. The tolerance unless classified ±0.2mm
  - 6. J2, J11: Molex 532610671 or Compatible
  - 7. J3: Molex 532610271 or Compatible
  - 8. J5, J23, J25: Molex 532610471 or Compatible
  - 9. J8: Molex 532611071 or Compatible

- 10. J9, J30: OMRON XF2M-3015-1A or Compatible
- 11. J12: OMRON XF2M-0615-1A or Compatible
- 12. J13: OMRON XF2M-5015-1A or Compatible
- 13. J16: Molex 894000610 or Compatible
- 14. J17: Molex 532610571 or Compatible

- 15. J31: OMRON XF2M-2415-1A or Compatible

007					
006					
005					
004					
003					
002	REMOVE J7 - J10 - J27	Nini	2021/12/14		
001	NEW DRAWING	Nini	2021/05/05		
REV		REV BY		REVISER	DATE

PART NO:	HIA128800T004ZZC06
DRAWING NAME:	LMD-HIA128800T004ZZC06
TITLE:	LCD MODULE DRAWING

	Design	Nini Chen		Surface	Material	Thickness	Quantity
	Check	Marcos Lu					
Approve	Daniel Lin	Unit	MM	Scale	FIT	Page	2/2
久正光电股份有限公司 POWER TIP TECHNOLOGY CORPORATION					4-HOLE Ø3.4 4-PAD Ø5.2	4-HOLE Ø3.5 4-PAD Ø6.5	Level
				Tolerance (mm)	1 ~ 4 4 ~ 16 16 ~ 63 63 ~ 250 250 ~ 1000		

# LCM包裝規格書

## LCM Packaging Specifications

Approve	Check	Contact
Marcus	Bright	Nini

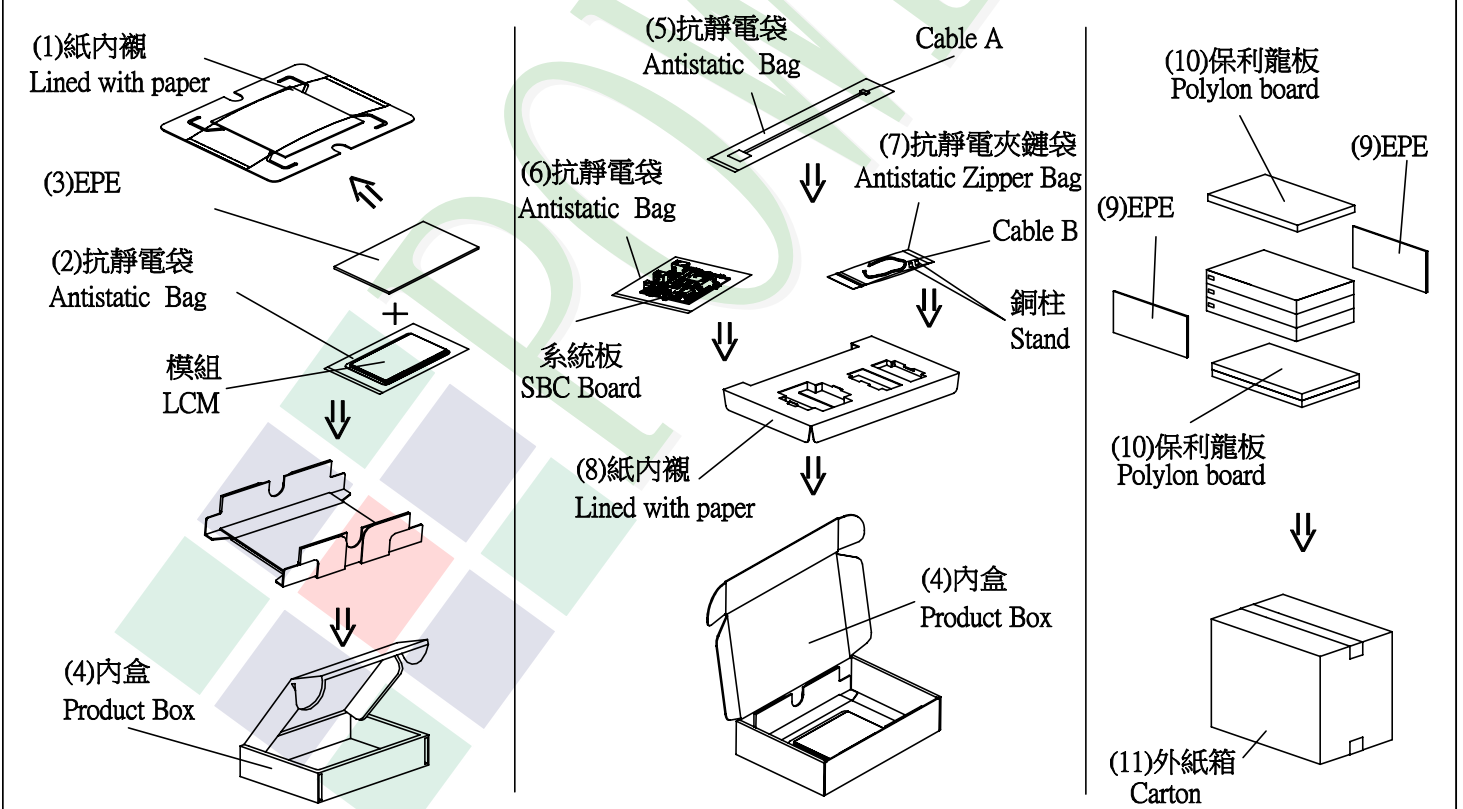
### 1. 包裝材料規格表 (Packaging Material) : (per carton)

No.	Item	Model	Dimensions (mm)	1Pcs Weight	Quantity	Total Weight
1	模組 (LCM)	PH128800T004-ZZC06	254.96 X 173.6 X 8.5	0.42	3	1.26
2	紙內襯 (1)Lined with paper	BX00000000136	538 X 384	0.13	3	0.39
3	抗靜電袋(2)Antistatic Bag	BAG0000000021	240 X 300	0.008	3	0.024
4	舒美墊(3) EPE	FOAM000000047	350 X 255 X 5	0.011	3	0.033
5	內盒(4)Product Box	BX00000000135	458 X 300 X 62	0.31	3	0.93
6	抗靜電袋(5)Antistatic Bag	BAG350120ARABA	120X 350	0.005	3	0.015
7	線材(CABLE A)	CB00000000196	L=400mm	0.011	3	0.033
8	抗靜電袋(6)Antistatic Bag	BAG150120ARABA	150 X 120	0.003	3	0.009
9	系統板(SBC Board)	—————	87 X 118.1X21.5	0.083	3	0.249
10	抗靜電夾鏈袋(7)Antistatic Zipper Bag	BAG0000000050	90X130	0.007	3	0.021
11	線材(CABLE B)	CB00000000201	L=250mm	0.003	3	0.009
12	銅柱(Stand)	OTSPACER00024	φ 4.5X 6.7	0.0007	6	0.0042
13	紙內襯 (8)Lined with paper	BX00000000137	516 X 367	0.043	3	0.129
14	舒美墊(9) EPE	OTFOAMEP0003BA	333 X 218 X 10	0.02	2	0.04
15	保利龍板(10)Poylon board	OTPLB00PL10ABA	440 X 320 X 5	0.01	3	0.03
16	外紙箱(11)Carton	BX47334524CCBA	473X 345 X 240	1.3	1	1.3

2. 一整箱總重量 (Total LCD Weight in carton) : 4.48 Kg±10%

3. 單箱數量規格表 (Packaging Specifications and Quantity) :

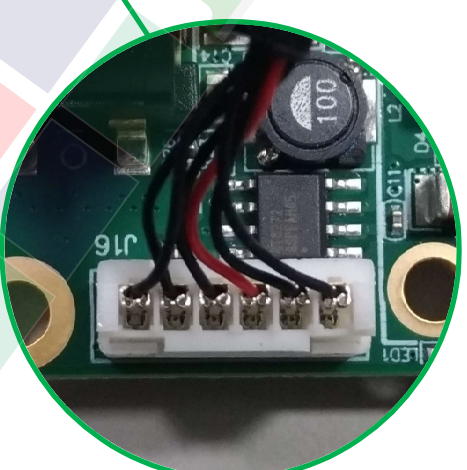
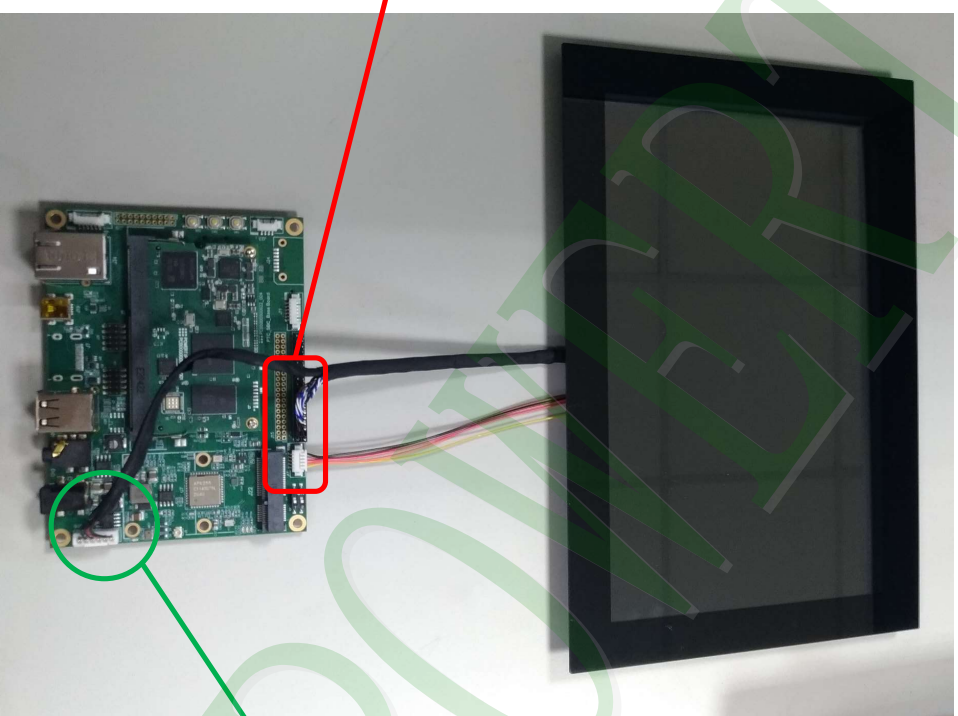
(1)LCM quantity per small box : no per lined with paper	1	x no of small box	1	=	1
(2)Total LCM quantity in carton : quantity per big box	1	x no of cartons	3	=	3



### 特 記 事 項 (REMARK)

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# HIA128800T004ZZC06 Assembly Guide (TOP)



# HIA128800T004ZZC06 Assembly Guide (BOTTOM)

